Amendments to the Specification:

Page 11, amend the paragraph beginning on line 13 to read as follows:

According to the mounting method of this invention, each of the values for ah1, ah2, aS1, aS2, v1 and v2 are defined such that the height for each of the opposing surfaces of the semiconductor element has a substantially constant value H relative to each of the electrode surfaces of the substrate when the semiconductor element 1 is face-mounted on the substrate. Among the six values described above, at least two values are predetermined and each of the remaining values is determined corresponding thereto. That is, each of the values is determined and prepared such that the constant height H constitutes a height that is in proportion to (ah1 + v1/aS1) or (ah2 + v2/aS2). In determining each of the values, the nature of the surface of the region in contact with and covered with the solder is of course taken into consideration. While the area for the solder-underlying region is expressed as aS1 and aS2 in the foregoing explanation, they are expressed as aS'1 and aS'2 in Figs. 4 and 5 since volumes of the solder to be prepared are different. However, in the general description, such areas of the solder-underlying regions are typically expressed as aS1 and aS2.